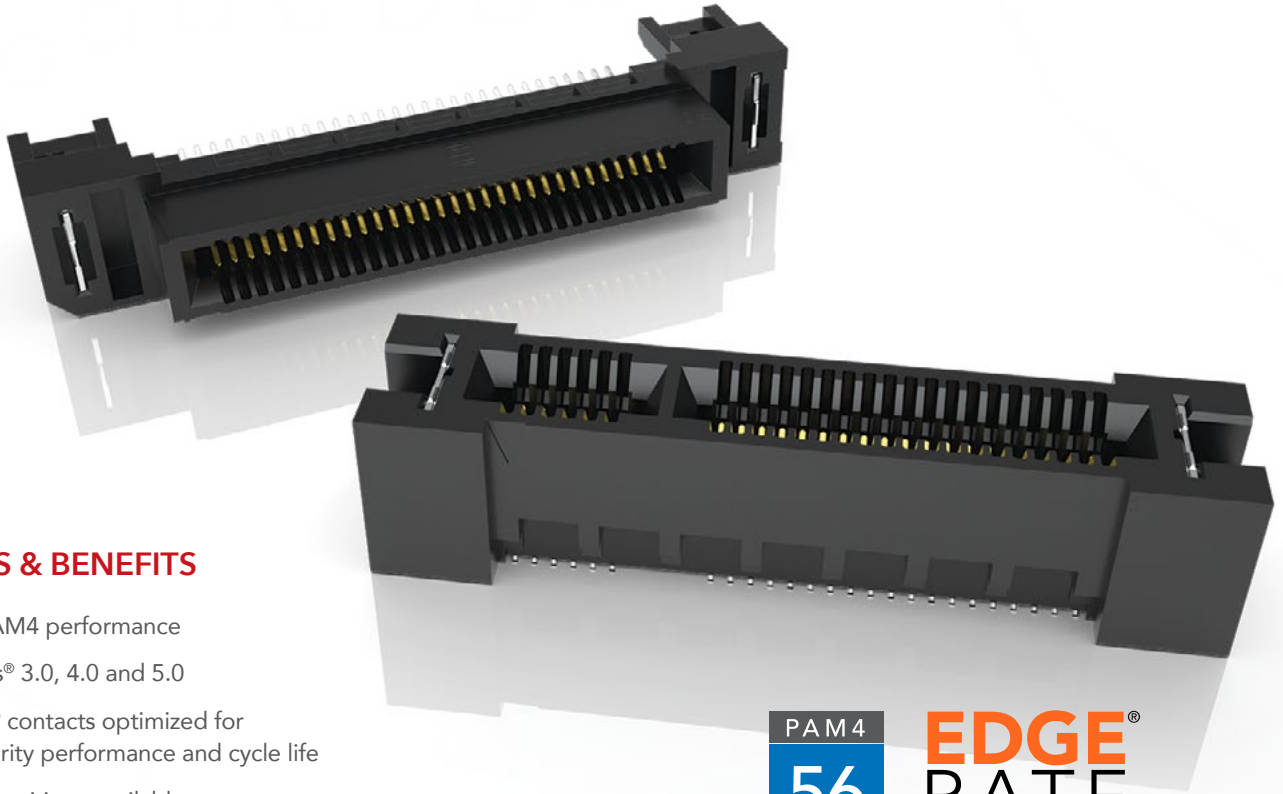


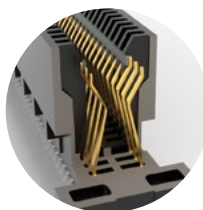
# HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH



## FEATURES & BENEFITS

- 56 Gbps PAM4 performance
- PCI Express® 3.0, 4.0 and 5.0
- Edge Rate® contacts optimized for signal integrity performance and cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available



Rugged tuck beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

## KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	0.8 A (12 pins)	300 VAC	Yes
HTEC8	0.80 mm	40-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC	Yes
HSEC8	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC	Yes

**(0.80 mm) .0315" PITCH • RIGHT-ANGLE & EDGE MOUNT SOCKET**

HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	RA	OTHER OPTIONS	"X"R
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09, 10, 13, 20,  
25, 30, 40, 49,  
50, 60

**-01**  
= (1.60 mm) .062"  
thick card

**-L**  
= 10 μ" (0.25 μm)  
Gold on contact area,  
Matte Tin on tail

**-S**  
= 30 μ" (0.76 μm)  
Gold on contact area,  
Matte Tin on tail

**-BL**  
= Board Locks (09, 13,  
25, 40, 49, 50, 60 only)

**-L2**  
= ECDP Latching  
(09, 13, 25, 49 only)

Leave blank for  
Tray Packaging

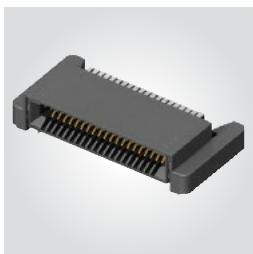
**-TR**  
= Tape & Reel

**-FR**  
= Full Reel  
Tape & Reel Packaging  
(must order max.  
quantity per reel;  
contact Samtec for  
quantity breaks)

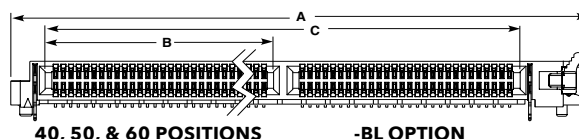
**HSEC8-RA**

**Card Mates:**  
(1.60 mm) .062"  
thick card,  
HSC8

**Cable Mates:**  
ECDP

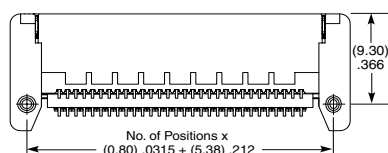


POSITIONS PER ROW	A	B	C
40	(43.80) 1.724	(18.90) .744	(36.60) 1.441
50	(51.80) 2.039	(22.90) .902	(44.60) 1.756
60	(59.80) 2.354	(26.90) 1.059	(52.60) 2.071
40-BL	(51.30) 2.020	(18.90) .744	(36.60) 1.441
50-BL	(59.30) 2.335	(22.90) .902	(44.60) 1.756
60-BL	(67.30) 2.650	(26.90) 1.059	(52.60) 2.071

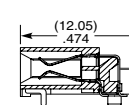
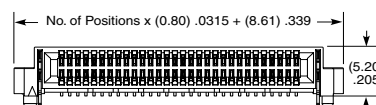


40, 50, & 60 POSITIONS

-BL OPTION



10, 20 & 30 POSITIONS



View complete specifications at: [samtec.com?HSEC8-RA](http://samtec.com?HSEC8-RA)

HSEC8	1	POSITIONS PER ROW	01	PLATING OPTION	D	EM2
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10, 20, 30, 40,  
50, 60

**-L**  
= 10 μ" (0.25 μm)  
Gold on contact area,  
Matte Tin on tail

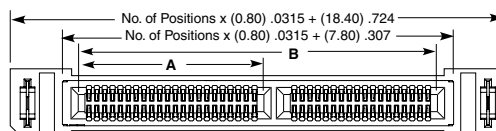
**-S**  
= 30 μ" (0.76 μm)  
Gold on contact area,  
Matte Tin on tail

**-EM2**  
= (1.60 mm) .062"  
thick PCB

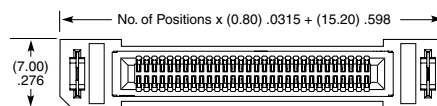
**HSEC8-EM**

**Card Mates:**  
(1.60 mm) .062"  
thick card,  
HSC8

**Cable Mates:**  
ECDP

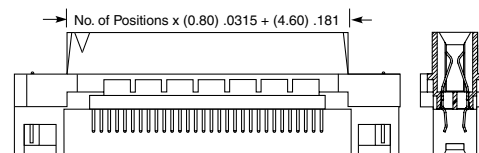


40, 50 & 60 POSITIONS



10, 20 & 30 POSITIONS

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071



**Note:**  
Some sizes, styles and  
options are non-standard,  
non-returnable.

View complete specifications at: [samtec.com?HSEC8-EM](http://samtec.com?HSEC8-EM)

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Authorized Distributor

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